Silicon Carbide Schottky Diode 650 V, 30 A

FFSH3065B

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size & cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 144 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- AEC-Q101 Qualified
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

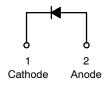
Applications

- Automotive HEV-EV Onboard Chargers
- Automotive HEV-EV DC-DC Converters



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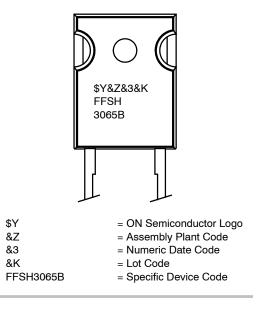


Schottky Diode



TO-247-2LD CASE 340DA

MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

FFSH3065B

Symbol	Parameter	Value	Unit	
V _{RRM}	Peak Repetitive Reverse Voltage		650	V
E _{AS}	Single Pulse Avalanche Energy (Note 1)		144	mJ
١ _F	Continuous Rectified Forward Current @ T _C <	30	A	
	Continuous Rectified Forward Current @ T_C <	37		
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	1100	А
		T _C = 150°C, 10 μs	1000	А
I _{F,SM}			110	A
Ptot	Power Dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	268	W
		T _C = 150°C	45	W
T _J , T _{STG}	Operating and Storage Temperature Range		–55 to +175	°C
	TO247 Mounting Torque, M3 Screw	60	Ncm	

ABSOLUTE MAXIMUM RATINGS (T_C = 25° C unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. E_{AS} of 144 mJ is based on starting $T_J = 25^{\circ}C$, L = 0.5 mH, $I_{AS} = 24$ A, V = 50 V.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ ext{ heta}JC}$	Thermal Resistance, Junction to Case, Max	0.56	°C/W

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V _F	Forward Voltage	$I_{F} = 30 \text{ A}, \text{ T}_{C} = 25^{\circ}\text{C}$	-	1.38	1.7	V
		$I_{F} = 30 \text{ A}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	1.6	2.0	
		I _F = 30 A, T _C = 175°C	-	1.72	2.4	
I _R	Reverse Current	$V_R = 650 \text{ V}, \text{ T}_C = 25^{\circ}\text{C}$	-	0.5	40	μΑ
		$V_{R} = 650 \text{ V}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	1	80	
		$V_{R} = 650 \text{ V}, \text{ T}_{C} = 175^{\circ}\text{C}$	-	2	160	
Q _C	Total Capacitive Charge	V = 400 V	-	73	-	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	1260	-	pF
		V _R = 300 V, f = 100 kHz	-	115	-	
		V _R = 600 V, f = 100 kHz	-	104	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping
FFSH3065B	FFSH3065B	TO-247-2LD (Pb-Free / Halogen Free)	30 Units / Tube

FFSH3065B

TYPICAL CHARACTERISTICS

(T_J = 25°C unless otherwise noted)

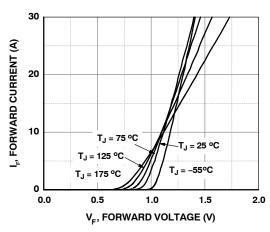


Figure 1. Forward Characteristics

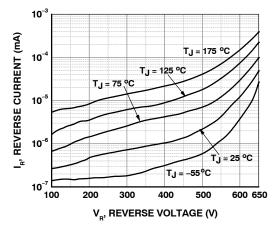
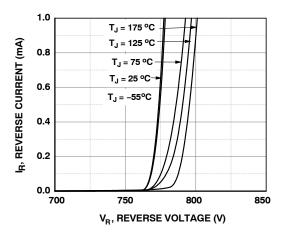
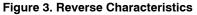
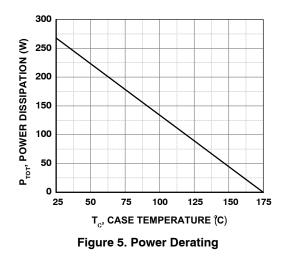
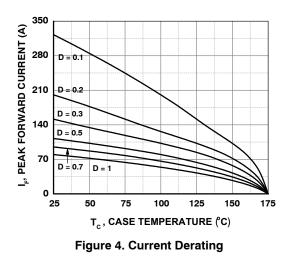


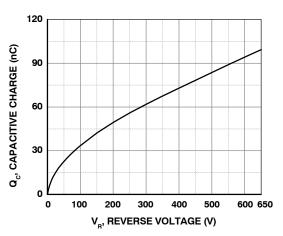
Figure 2. Reverse Characteristics













FFSH3065B

TYPICAL CHARACTERISTICS

(T_J = 25°C unless otherwise noted)

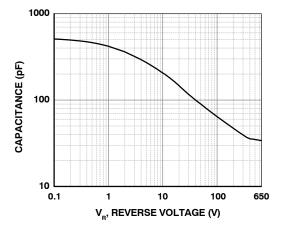


Figure 7. Capacitance vs. Reverse Voltage

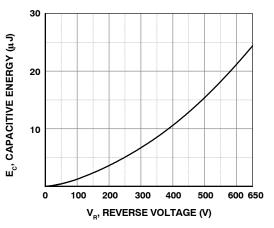


Figure 8. Capacitance Stored Energy

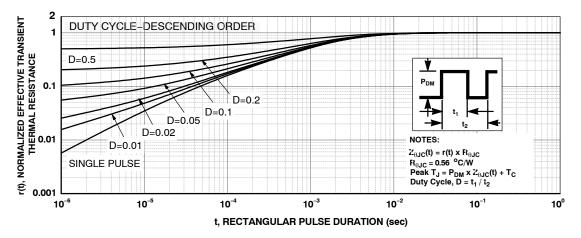
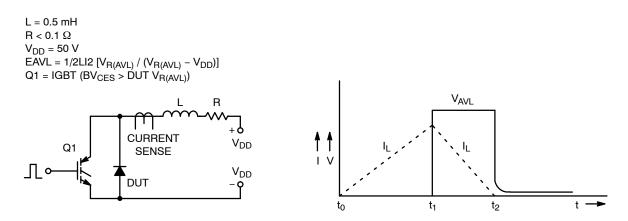


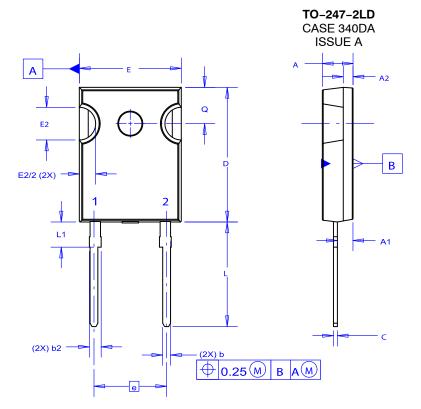
Figure 9. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS





PACKAGE DIMENSIONS

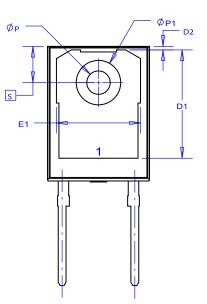


NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
- FLASH, AND TIE BAR EXTRUSIONS. B. ALL DIMENSIONS ARE IN MILLIMETERS.

- C. DRAWING CONFORMS TO ASME Y14.5 2009.D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.





	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
с	0.51	0.61	0.71		
D	20.32	20.57	20.82		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E	15.37	15.62	15.87		
E1	12.81	~	~		
E2	4.96	5.08	5.20		
е	~	11.12	~		
L	15.75	16.00	16.25		
L1	3.69	3.81	3.93		
ØР	3.51	3.58	3.65		
Ø P 1	6.60	6.80	7.00		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		

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